It is our great pleasure to welcome you to the Embedded & Cyber-Physical Environments Symposium associated with the 39th IEEE International Computer Software and Applications Conference, COMPSAC 2015, organized this year in the wonderful city of Taichung, Taiwan.

The Embedded & Cyber-Physical Environments Symposium brings together researchers and practitioners to create systems that consist of disparate components, using disparate metrics and methods. These systems have deeply embedded distributed computation in distributed infrastructures ranging in scale from micro to very large. Such systems contain not only complex physical dynamics (physical systems), but non-trivial distributed computation (cyber systems) and communication (network systems). Multidisciplinary work, research and development software prototypes, industry-university collaborations, all based on new emerging and critical technologies are of particular interest to this symposium.

Following the tradition of all COMPSAC conferences, each submission underwent a rigorous double-blind review process and was discussed by the program and organizing chairs during the PC meeting, which took place in Shanghai, in March 13-14, 2015. As the result of the process, from 15 submissions, we accepted 29% of the submissions as regular papers and 13% of the submission as short papers for inclusion into this year’s COMPSAC proceedings, published by IEEE CS. 4 regular papers, 2 short papers, in addition to a panel discussion and an invited talk will be presented across three sessions on Friday July 3.

We thank all the authors for submitting their research results to the conference, and the members of the Program Committee and external reviewers for their dedicated, expert and careful assessment of the submissions. We thank the conference organizers including the Standing Committee Chair, Carl Chang, Steering Chair, General chairs, and Program Chairs – Gang Huang, Ivica Crnkovic, and Pao-Ann Hsuing.

Organizing Committee

General Chairs
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